

Sintering carrier with
DBC mastercard.



Sintering carrier with
single substrates.

PiNK application and R&D services For soldering and sintering technology

Within a rapidly increasing and competitive market, fast process developments with highest yield and reliability are needed to satisfy the ever-growing demands for modern electronic devices.

With its application and R&D services PiNK supports its customers from the very beginning of packaging development to series production. Starting with equipment demonstrations, soldering and sintering trials, PiNK provides feasibility studies of new packaging concepts incl. package assembly.

PiNK also evaluates and improves UPH, yield and quality. Essential process know-how is given to the customer's engineers and technicians by trainings. In case of process issues PiNK offers continuous support.

Range of services

- Consulting and concept development
- Trials and demonstrations for customers
- Feasibility studies
- Prototype assembly
- Process development
- Process training and support

Applications for soldering/sintering

- Die-attach
- Substrate to baseplate
- Die top side connection
- Double-sided packaging
- Leadframe connection
- Multi-layer packaging

PiNK equipment

- VADU soldering systems
- Sintering systems SIN 20 and SIN 200+
- Plasma cleaning equipment
- Circulating air oven

Additional equipment

- Pick & place machine
- Stencil printer

Test devices

- Test DBCs with Au, Ag, Cu metallization
- Dummy Si chips
- AMB with Cu metallization

In-house quality inspection

- SAM analysis
- Shear and peel testing
- Microscopy
- Mandrel bending test
- Surface tension measurement
- IR camera

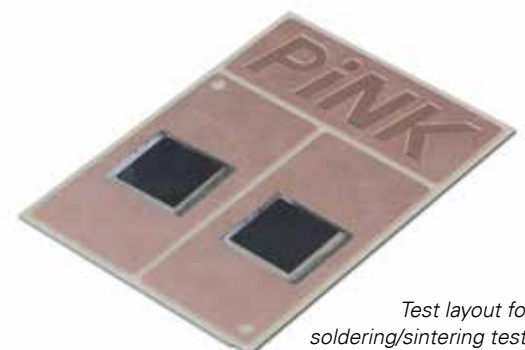
External analysis

- X-Ray
- Cross sectioning
- REM/EDX analysis

PiNK GmbH

Thermosysteme

Am Kessler 6
97877 Wertheim
Germany
T +49 (0) 93 42 919-0
F +49 (0) 93 42 919-111
application@pink.de
www.pink.de



Test layout for
soldering/sintering test.